

# TRAPPING MECHANISM OF CHARGE TRAP CAPACITOR WITH $\text{Al}_2\text{O}_3/\text{HIGH-k}/\text{Al}_2\text{O}_3$ MULTILAYER

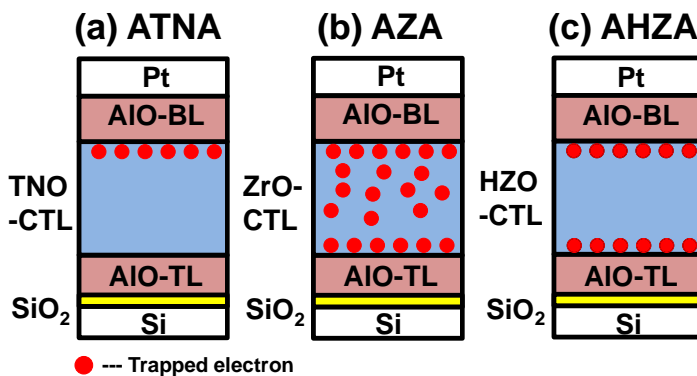
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Charge trap flash memories with  $\text{Al}_2\text{O}_3/\text{High-k}/\text{Al}_2\text{O}_3$  multilayer have been considered to reduce leakage current and improve electrical properties under low operation voltage for further device scaling down capability [1, 2]. In case of charge trap capacitor with  $\text{SiO}_2/\text{SiN}/\text{Al}_2\text{O}_3$  multilayer, the several mechanism have been proposed to recognize where injected electron is trapped. For example, the injected electrons are piled up in a center of SiN-charge trap layer (SiN-CTL) or interface between  $\text{SiO}_2$  tunneling layer (TL) and SiN-CTL or other interface between SiN-CTL and  $\text{Al}_2\text{O}_3$ -blocking layer (AIO-BL) [3]. However, the trapping mechanism of the High-k-charge trap layer (High-k-CTL) is still not clear. In this paper, we focus on the trapping mechanism of High-k-CTLs, such as an amorphous  $(\text{Ta}/\text{Nb})\text{O}_x$  (TNO-CTL), a crystallized  $\text{ZrO}_2$  (ZrO-CTL) and a ferroelectric  $\text{HfZrO}_x$  (HZO-CTL), from the data of flatband voltage ( $V_{\text{fb}}$ ) characteristics under program mode.

Pt-gated charge trap capacitors with  $\text{Al}_2\text{O}_3/(\text{Ta}/\text{NbO}_x)/\text{Al}_2\text{O}_3$  (ATNA),  $\text{Al}_2\text{O}_3/\text{ZrO}_2/\text{Al}_2\text{O}_3$  (AZA), and  $\text{Al}_2\text{O}_3/\text{HfZrO}_x/\text{Al}_2\text{O}_3$  (AHZA) were prepared by atomic layer deposition and annealing processes. The thicknesses of the TNO, ZrO and HZO-CTLs were varied from 5 to 20 nm while  $\text{Al}_2\text{O}_3$ -tunneling layer (AIO-TL) and AIO-BL were kept to be 8 nm thickness.

We observed the different  $V_{\text{fb}}$  shift behavior among ATNA, AZA and AHZA under program mode. The  $V_{\text{fb}}$  shift of AZA is much larger than those of ATNA and AHZA. We study the trapping mechanism of three capacitors from thickness dependence of the TNO, ZrO and HZO-CTLs on  $V_{\text{fb}}$  shift. The schematic illustrations of these trapping mechanism of ATNA, AZA and AHZA were shown in Fig. 1. In the ATNA case, the  $V_{\text{fb}}$  shift satisfy a linear equation as a function of the thickness of TNO-CTL, indicating that the injected electrons are dominantly located at the TNO-CTL/AIO-BL interface. On the other hand, the  $V_{\text{fb}}$  shift of the AZA satisfy a quadratic equation, indicating that the location of electron is at both AIO-TL/ZrO-CTL and ZrO-CTL/AIO-BL interfaces, and in bulk ZrO-CTL. Finally, the injected electrons are piled up at both AIO-TL/HZO-CTL and HZO-CTL/AIO-BL interfaces in the AHZA. These trapping mechanisms result in the different  $V_{\text{fb}}$  shift behavior among ATNA, AZA and AHZA under program mode.



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**Figure 1 Systematics of trapping mechanism of (a) ATNA, (b) AZA, and (c) AHZA under program mode**

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